

MCF5272VM66 Information

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General Information

Parameter	Value
Part Number	MCF5272VM66
Description	MCF5272 V2CORE 4KSRAM
Material Type	Tested Packaged Device
<u>Life Cycle Description (code)</u>	PRODUCT STABLE GROWTH/MATURITY(3)
Status	Available

Package Information

Parameter	Value
Package Description	<u>MAPBGA 196 15*15*0.8P1.0</u>
JEDEC Pkg Description	PBGA-B196
Pin/Lead/Ball Count	196
Package Material	Plastic
Mounting Style	Surface Mount
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
<u>Pb-Free</u>	
<u>RoHS Compliant</u>	
<u>Halogen Free</u>	Yes
Product Content Report	<u>Product Content Report</u>
<u>2nd Level Interconnect</u>	e1
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Package Peak Temperature (°C)	260

Manufacturing and Qualification information

Parameter	Value
Micron Size (µm)	0.32
<u>Application/Qualification Tier</u>	COMMERCIAL, INDUSTRIAL

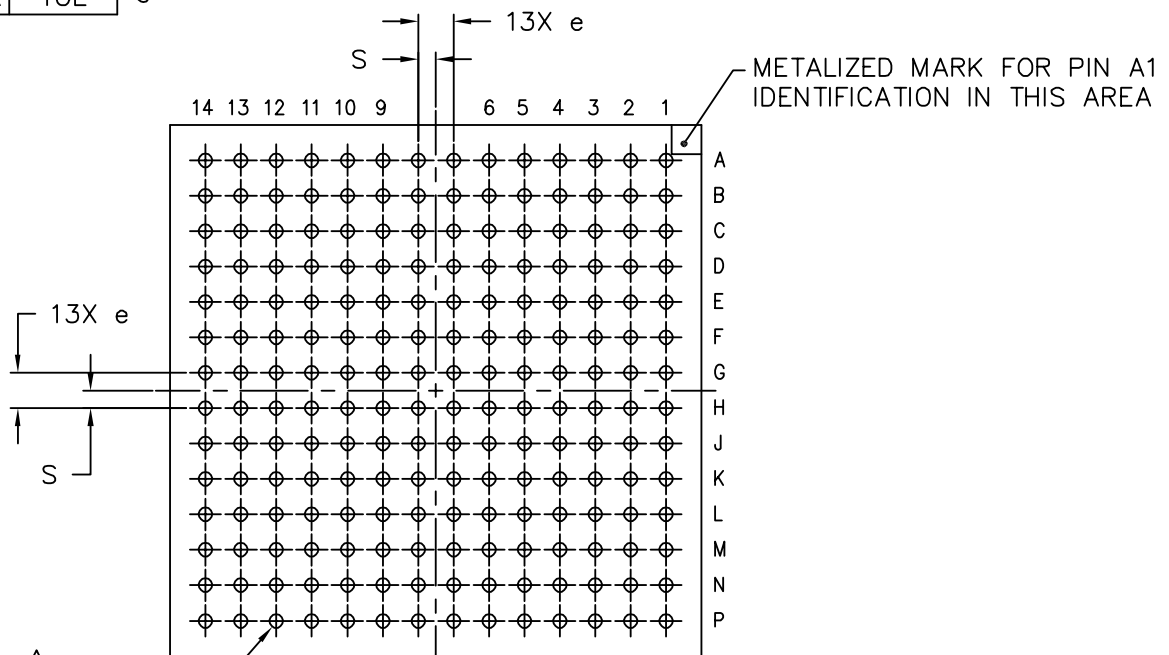
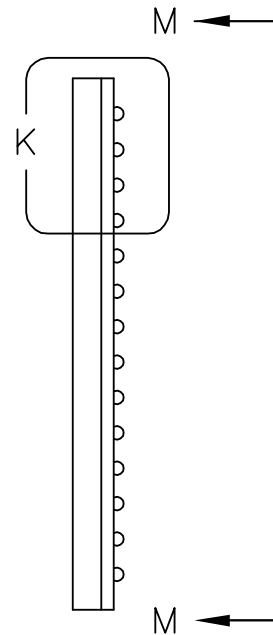
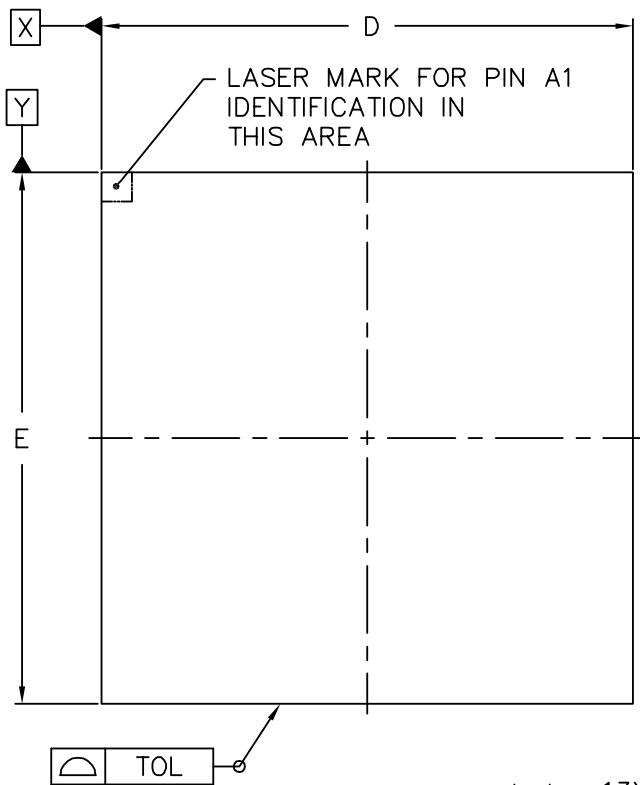
Ordering Information

Parameter	Value
Last Order Date	

Last Ship Date	
Minimum Package Quantity (MPQ)	126
MPQ Container	TRAY
Preferred Order Quantity (POQ)	1260
POQ Container	BOX
Leadtime (weeks)	12
Export Control Classification Number (US)	5A991
Harmonized Tariff (US)	8542.21.8079
<u>Budgetary Price QTY 1000+ (\$US)</u>	\$10.57
Order	

Product/Process Change Notice (PCN)

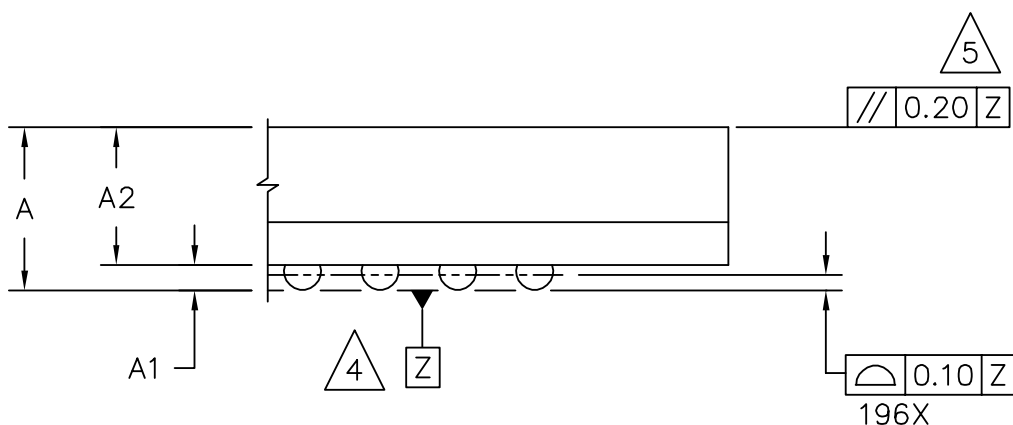
Number	Type	Title	Issue Date	Effectivity Date
10742	Product Bulletin	<u>KLM PACKING CHANGE FOR TRAY DEVICES</u>	03-28-2005	04-02-2005



3 196X ϕb	$\phi 0.15$ (M) Z X Y
	$\phi 0.08$ (M) Z

VIEW M-M

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TITLE: 196 I/O STD MAP BGA, 15 X 15 PKG, 1.00 PITCH			DOCUMENT NO: 98ARH98217A		REV: A
			CASE NUMBER: 1128C-01		15 JUL 2005
			STANDARD: NON-JEDEC		



DETAIL K
ROTATED 90° CLOCKWISE

DIM	MIN	MAX	NOTES
A	1.25	1.60	1. DIMENSIONS ARE IN MILLIMETERS. 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994. 3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z. 4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS. 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
A1	0.27	0.47	
A2	1.16	REF	
b	0.45	0.55	
D	15.00	BSC	
E	15.00	BSC	
e	1.00	BSC	
S	0.50	BSC	
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